

Dual D-Type Flip-Flop with Preset and Clear

MM74HCT74

General Description

The MM74HCT74 utilizes advanced silicon—gate CMOS technology to achieve operation speeds similar to the equivalent LS–TTL part. It possesses the high noise immunity and low power consumption of standard CMOS integrated circuits, along with the ability to drive 10 LS–TTL loads.

This flip—flop has independent data, preset, clear, and clock inputs and Q and \overline{Q} outputs. The logic level present at the data input is transferred to the output during the positive—going transition of the clock pulse. Preset and clear are independent of the clock and accomplished by a low level at the appropriate input.

The 74HCT logic family is functionally and pin-out compatible with the standard 74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to VCC and ground.

MM74HCT devices are intended to interface between TTL and NMOS components and standard CMOS devices. These parts are also plug–in replacements for LS–TTL devices and can be used to reduce power consumption in existing designs.

Features

- Typical Propagation Delay: 18 ns
- Low Quiescent Current: 80 μA Maximum (74HCT Series)
- Low Input Current: 1 μA Maximum
- Fanout of 10 LS-TTL Loads
- Meta-stable Hardened
- These Devices are Pb-Free, Halide Free and are RoHS Compliant

Connection Diagram

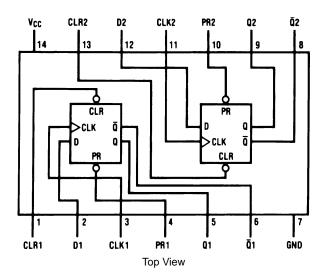
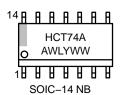


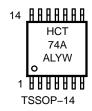
Figure 3. Pin Assignments for SOIC and TSSOP





MARKING DIAGRAM





HCT74A = Specific Device Code
A = Assembly Location

WL, L = Wafer Lot Y = Year WW, W = Work Week

ORDERING INFORMATION

See detailed ordering and shipping information on page 7 of this data sheet.

MM74HCT74

TRUTH TABLE

Inputs			Out	outs	
PR	CLR	CLK	D	Q	Q
L	Н	Х	Х	Н	L
Н	L	Х	Х	L	Н
L	L	Х	Х	H (Note 4)	H (Note 4)
Н	Н	↑	Н	Н	L
Н	Н	↑	L	L	Н
Н	Н	L	Х	Q0	Q0

Q0 = the level of Q before the indicated input conditions were established.

4. This configuration is nonstable; that is, it will not persist when preset and clear inputs return to their inactive (HIGH) level.

Logic Diagram

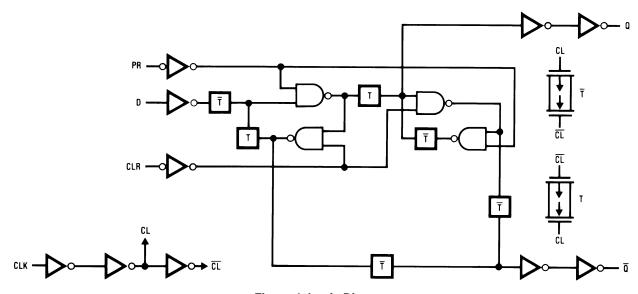


Figure 4. Logic Diagram

ABSOLUTE MAXIMUM RATINGS (Note 5)

Symbol	Parameter		Rating
V _{CC}	Supply Voltage		–0.5 to +7.0 V
V _{IN}	DC Input Voltage		–0.5 to V _{CC} + 0.5 V
V _{OUT}	DC Output Voltage		–0.5 to V _{CC} + 0.5 V
I _{IK} , I _{OK}	Clamp Diode Current		±20 mA
I _{OUT}	DC Output Current, per Pin		±25 mA
Icc	DC V _{CC} or GND Current, per Pin		±50 mA
T _{STG}	Storage Temperature Range		–65°C to +150°C
P _D	Power Dissipation	S.O. Package Only	500 mW
T _L	Lead Temperature (Soldering 10	O Seconds)	260°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

5. Unless otherwise specified all voltages are referenced to ground.

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RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	Supply Voltage	4.5	5.5	V
V _{IN} , V _{OUT}	DC Input or Output Voltage	0	V _{CC}	V
T _A	Operating Temperature Range	- 55	+125	°C
t _r , t _f	Input Rise or Fall Times	-	500	ns

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC CHARACTERISTICS ($V_{CC} = 5 V \pm 10\%$ (unless otherwise specified))

			T _A = 25°C		T _A = -40°C to 85°C	T _A = -55°C to 125°C	
Symbol	Parameter	Conditions	Тур	Gu	aranteed Lin	nits	Unit
V _{IH}	Minimum HIGH Level Input Voltage			2.0	2.0	2.0	V
V _{IL}	Maximum LOW Level Input Voltage			0.8	0.8	0.8	V
V _{OH}	Minimum HIGH Level Output Voltage	$V_{IN} = V_{IH}$ or V_{IL} , $ I_{OUT} = 20 \mu A$	VCC	V _{CC} – 0.1	V _{CC} - 0.1	V _{CC} - 0.1	V
		$V_{IN} = V_{IH} \text{ or } V_{IL}, I_{OUT} = 4.0 \text{ mA},$ $V_{CC} = 4.5 \text{ V}$	4.2	3.98	3.84	3.7	
		$V_{IN} = V_{IH} \text{ or } V_{IL}, I_{OUT} = 4.8 \text{ mA},$ $V_{CC} = 5.5 \text{ V}$	5.2	4.98	4.84	4.7	
V _{OL}	Maximum LOW Level Voltage	$V_{IN} = V_{IH}$ or V_{IL} , $ I_{OUT} = 20 \mu A$	0	0.1	0.1	0.1	V
		$V_{IN} = V_{IH} \text{ or } V_{IL}, I_{OUT} = 4.0 \text{ mA},$ $V_{CC} = 4.5 \text{ V}$	0.2	0.26	0.33	0.4	
		$V_{IN} = V_{IH} \text{ or } V_{IL}, I_{OUT} = 4.8 \text{ mA}, $ $V_{CC} = 5.5 \text{ V}$	0.2	0.26	0.33	0.4	
I _{IN}	Maximum Input Current	$V_{IN} = V_{CC}$ or GND, V_{IH} or V_{IL}	-	±0.5	±0.5	±1.0	μΑ
Icc	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND, $I_{OUT} = 0 \mu A$	-	2.0	20	80	μΑ
		V _{IN} = 2.4 V or 0.5 V (Note 6)	-	0.3	0.4	0.5	mA

^{6.} This is measured per input with all other inputs held at $\rm V_{CC}$ or ground.

AC CHARACTERISTICS (V_{CC} = 5.0 V, t_r = t_f = 6 ns, C_L = 15 pF, T_A = 25°C (unless otherwise noted))

Symbol	Parameter	Conditions	Тур	Guaranteed Limit	Unit
f _{MAX}	Maximum Operating Frequency from Clock to Q or Q		50	30	MHz
t _{PHL} , t _{PLH}	Maximum Propagation Delay Clock to Q or Q		18	30	ns
t _{PHL} , t _{PLH}	Maximum Propagation Delay from Preset or Clear to Q or Q		18	30	ns
t _{REM}	Minimum Removal Time, Preset or Clear to Clock		-	20	ns
t _S	Minimum Setup Time Data to Clock		-	20	ns
t _H	Minimum Hold Time Clock to Data		-3	0	ns
t _W	Minimum Pulse Width Clock, Preset or Clear		8	16	ns

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AC CHARACTERISTICS (V_{CC} = 5.0 V ±10%, C_L = 50 pF, t_f = t_f = 6 ns (unless otherwise noted))

			T _A =	25°C	$T_A = -40^{\circ}C$ to $85^{\circ}C$	
Symbol	Parameter	Conditions	Тур	Gua	aranteed Limits	Unit
f _{MAX}	Maximum Operating Frequency		-	27	21	MHz
t _{PHL} , t _{PLH}	Maximum Propagation Delay from Clock to Q or Q		21	35	44	ns
t _{PHL} , t _{PLH}	Maximum Propagation Delay from Preset or Clear to Q or $\overline{\mathbf{Q}}$		21	35	44	ns
t _{REM}	Minimum Removal Time Preset or Clear to Clock		_	20	25	ns
t _S	Minimum Setup Time Data to Clock		_	20	25	ns
t _H	Minimum Hold Time Clock to Data		-3	0	0	ns
t _W	Minimum Pulse Width Clock, Preset or Clear		9	16	20	ns
t _r , t _f	Maximum Clock Input Rise and Fall Time		-	500	500	ns
t _{THL} , tTLH	Maximum Output Rise and Fall Time		-	15	19	ns
C _{PD}	Power Dissipation Capacitance (Note 7)	(per flip-fl _{IN} op)	10	-	_	pF
C _{IN}	Maximum Input Capacitance		5	10	10	pF

^{7.} C_{PD} determines the no load dynamic power consumption, $P_D = C_{PD} \ V_{CC}^2 \ f + I_{CC} \ V_{CC}$, and the no load dynamic current consumption, $I_S = C_{PD} \ V_{CC} \ f + I_{CC}$.

ORDERING INFORMATION

Part Number	Package	Shipping [†]
MM74HCT74M	SOIC-14, Case 751A-03 (Pb-Free, Halide-Free)	55 Units / Tube
MM74HCT74MX	SOIC-14, Case 751A-03 (Pb-Free, Halide-Free)	2500 Units / Tape & Reel
MM74HCT74MTCX	TSSOP-14, Case 948G-01 (Pb-Free, Halide Free)	2500 Units / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

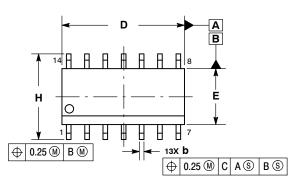


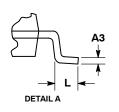


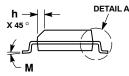
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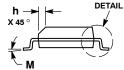
SOIC-14 NB CASE 751A-03 ISSUE L

DATE 03 FEB 2016





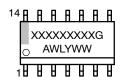




- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
 - ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 - DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT
 - MAXIMUM MATERIAL CONDITION.
 DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
- 5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE

	MILLIN	IETERS	INCHES	
DIM	MIN	MAX	MIN	MAX
Α	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
АЗ	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
Е	3.80	4.00	0.150	0.157
е	1.27	BSC	0.050 BSC	
Н	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
M	0 °	7°	0 °	7°

GENERIC MARKING DIAGRAM*

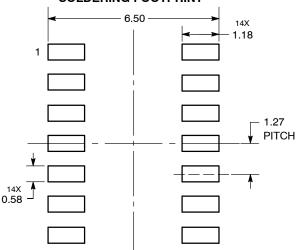


XXXXX = Specific Device Code Α = Assembly Location

WL = Wafer Lot Υ = Year WW = Work Week = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

C SEATING PLANE

STYLES ON PAGE 2

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^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DATE 03 FEB 2016

STYLE 1: PIN 1. COMMON CATHODE 2. ANODE/CATHODE 3. ANODE/CATHODE 4. NO CONNECTION 5. ANODE/CATHODE 6. NO CONNECTION 7. ANODE/CATHODE 8. ANODE/CATHODE 9. ANODE/CATHODE 10. NO CONNECTION 11. ANODE/CATHODE 12. ANODE/CATHODE 13. NO CONNECTION 14. COMMON ANODE	STYLE 2: CANCELLED	STYLE 3: PIN 1. NO CONNECTION 2. ANODE 3. ANODE 4. NO CONNECTION 5. ANODE 6. NO CONNECTION 7. ANODE 8. ANODE 9. ANODE 10. NO CONNECTION 11. ANODE 12. ANODE 13. NO CONNECTION 14. COMMON CATHODE	STYLE 4: PIN 1. NO CONNECTION 2. CATHODE 3. CATHODE 4. NO CONNECTION 5. CATHODE 6. NO CONNECTION 7. CATHODE 8. CATHODE 9. CATHODE 10. NO CONNECTION 11. CATHODE 12. CATHODE 13. NO CONNECTION 14. COMMON ANODE
STYLE 5: PIN 1. COMMON CATHODE 2. ANODE/CATHODE 3. ANODE/CATHODE 4. ANODE/CATHODE 5. ANODE/CATHODE 6. NO CONNECTION 7. COMMON ANODE 8. COMMON CATHODE 9. ANODE/CATHODE 10. ANODE/CATHODE 11. ANODE/CATHODE 12. ANODE/CATHODE 12. ANODE/CATHODE 13. NO CONNECTION 14. COMMON ANODE	STYLE 6: PIN 1. CATHODE 2. CATHODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE 7. CATHODE 8. ANODE 9. ANODE 10. ANODE 11. ANODE 12. ANODE 13. ANODE 14. ANODE	STYLE 7: PIN 1. ANODE/CATHODE 2. COMMON ANODE 3. COMMON CATHODE 4. ANODE/CATHODE 5. ANODE/CATHODE 6. ANODE/CATHODE 7. ANODE/CATHODE 8. ANODE/CATHODE 9. ANODE/CATHODE 10. ANODE/CATHODE 11. COMMON CATHODE 12. COMMON CATHODE 13. ANODE/CATHODE 14. ANODE/CATHODE	STYLE 8: PIN 1. COMMON CATHODE 2. ANODE/CATHODE 3. ANODE/CATHODE 4. NO CONNECTION 5. ANODE/CATHODE 6. ANODE/CATHODE 7. COMMON ANODE 8. COMMON ANODE 9. ANODE/CATHODE 10. ANODE/CATHODE 11. NO CONNECTION 12. ANODE/CATHODE 13. ANODE/CATHODE 14. COMMON CATHODE

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